

開発製品のご紹介

Introduction of developed products

延伸可能な電磁波シールドフィルム（開発中） Stretchable electromagnetic wave shielding film

▶ ミリ波など高周波帯域の**電磁波を遮蔽**

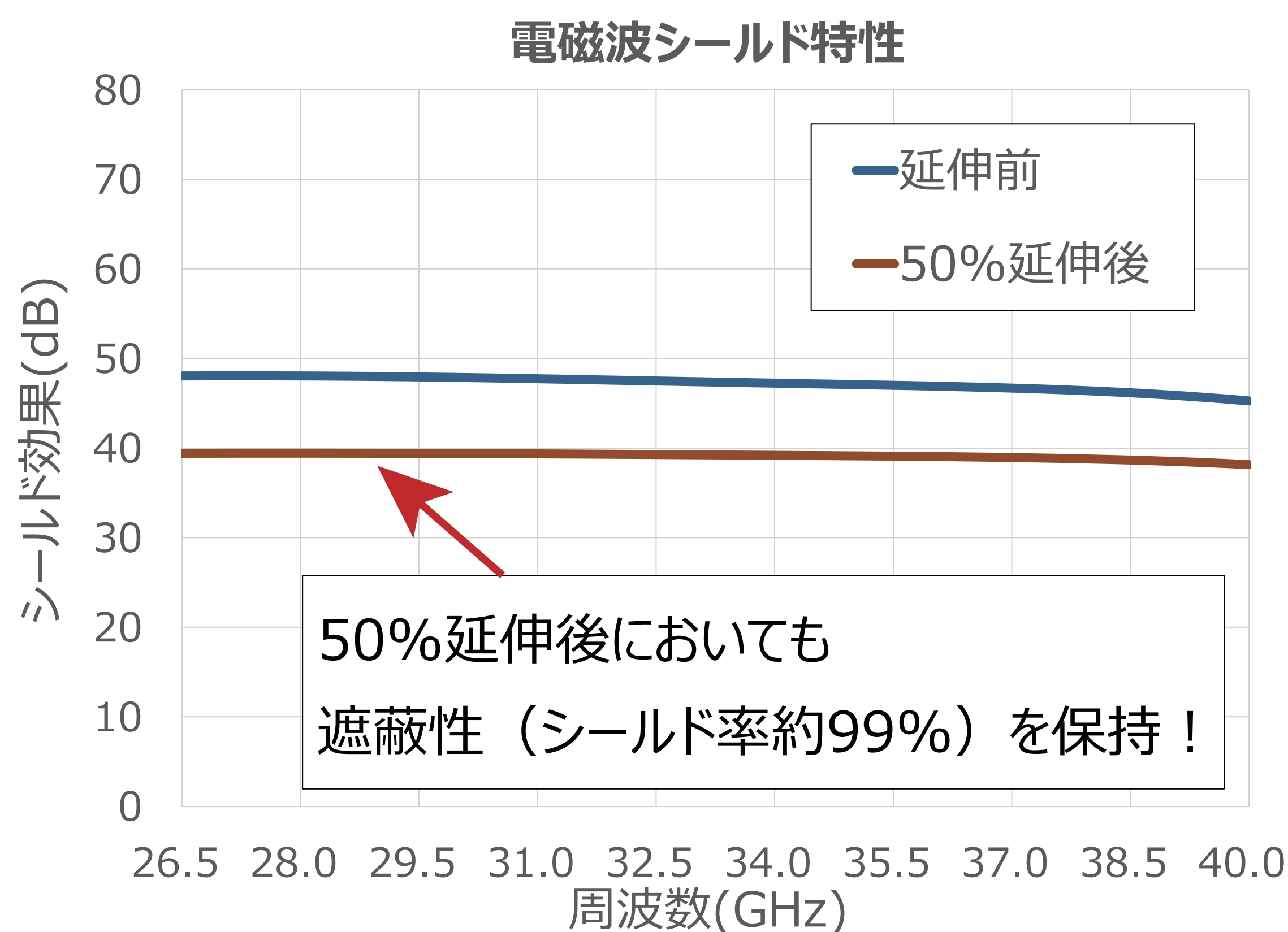
Blocks electromagnetic waves in high frequency bands such as millimeter waves.

▶ **延伸後**もシールド性を保持

Maintains shielding properties even after stretching.

▶ 成形用途にも対応可能

Also suitable for molding applications



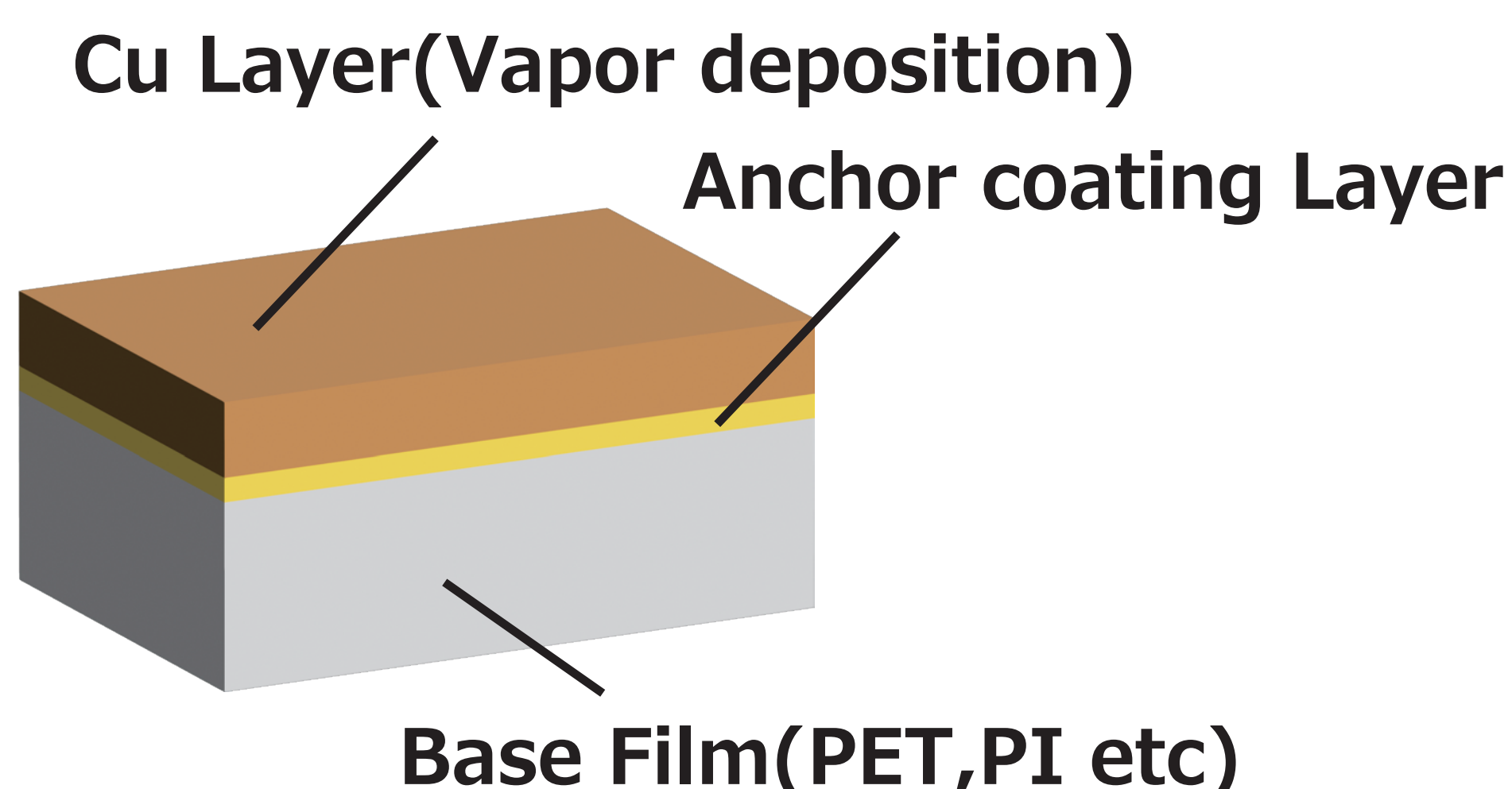
導電性薄膜フィルム（Cu 蒸着） Conductive film (Copper)

▶ 様々な基材（**PET**、**PI** など）に**導電性**付与

We can impart conductivity to various substrates (PET, PI, etc.)

▶ 銅箔代替、**めっきシード層**としても使用可能

It can also be used as a copper foil substitute and plating seed layer.



Cu蒸着膜 特性			
Cu膜厚(μm)	0.1	0.3	1.0
表面抵抗率(Ω/□)	2.0×10^{-1}	8.0×10^{-2}	1.7×10^{-2}
18μmめっき後 密着(N/cm)	PET基材	2.0	
	PI基材	7.2	

上記データは一定条件下で求めた測定値であり保証値ではありません。

The above data were obtained from measurements under specific conditions and not guaranteed values.